

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.01	1.06	0.04
		Silicon (Si)	7440-21-3	0.98	98.94	3.35
		Subtotal		0.99	100	3.39
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.42	100.0	1.44
		Subtotal		0.42	100	1.44
Post-plating	Pure metal	Tin (Sn)	7440-31-5	3.5	100.0	12
		Subtotal		3.5	100	12
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.05
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.02	0.03	0.05
		Iron (Fe)	7439-89-6	0.05	0.1	0.17
		Copper (Cu)	7440-50-8	50.74	99.84	173.92
		Subtotal		50.83	100	174.19
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.61	6.0	8.96
		Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.05	7.0	10.45
		Silica fused	60676-86-0	37.46	86.0	128.4
		Carbon black	1333-86-4	0.44	1.0	1.49
		Subtotal		43.56	100	149.3
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01	2.0	0.05
		Silver (Ag)	7440-22-4	0.02	2.5	0.06
		Lead (Pb)	7439-92-1	0.68	95.5	2.32
		Subtotal		0.71	100	2.43
		Total		100.01	100	342.75

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